REMARKS/ARGUMENTS

The claims are amended to refer to embodiment for which evidence of special results is provided in the specification (e.g. see Tables of Examples and comparative Examples results in the specification at page 14 et seq). Support for amendments and also the new claims is also at paragraph bridging pages 12-13 and page 8, lines 19 to 24 (preferred resin combination as now claimed).

Claims 1-2 and 4-6 are rejected as obvious over Amaya in view of Araki and Takezawa. Takezawa is relied on to show a thermosetting conductive adhesive paste which has metal powder that meets the high and low melting point requirements of the present invention. First of all, the problem to be solved by the invention of the present invention is different from that of Takezawa '652. That is, an object of the present invention is to solve the problems concerning bonding-property between an

internal electrode(s) and the external electrode, which the above-mentioned thermosetting conductive paste has had, and to provide a multilayer ceramic electronic part having high reliabilities which is suitable for its mounting on a substrate and for its plating-treatment as mentioned on page 3, lines 26 to 33 of the present specification. To accomplish this object, the internal electrode has the specific constitution as defined in the revised new Claim 1. By employing such a constitution as defined in new Claim 1 of the present invention, a metal-to-metal junction is formed between the internal electrode(s) and the external electrode whereby bonding-property is improved (e.g. see Examples and comparison Examples in the specification).

On the other hand, Takezawa '652 is directed to a conductive adhesive to electrically connect a substrate and an electronic element as mentioned at the paragraph [0002] thereof. When a conductive adhesive is used for a packaging structure as in Takezawa '652, the portion on which the adhesive is coated and cured are exposed to outside and markedly affected by moisture in the air. Thus, an object of Takezawa '652 is to provide a conductive adhesive and a packaging structure that can maintain a

moisture-proof reliability as mentioned at the paragraph [0007] thereof.

It is to be noted that in Takezawa '652 there is no description nor suggestion that the conductive adhesive can be used for formation of an external electrode. Also, as detailed below, modifying Takezawa '652 to meet the presently claimed requirements is taught away from by Takezawa '652.

Concerning teaching away from the presently claimed invention, Takezawa '652 (which is now US Patent No. 6,524,721 B2) teaches in paragraph [0021] that electric connection is secured by adding second particles which satisfy the relationship of the standard electrode potentials as follows:

(first particles) > (electrodes) > (second particles)

This is explained at lines 1 to 7 of paragraph [0022] of Takezawa '652 that "(w)hen the standard electrode potential of the second particles is relatively lower than that of the electrodes, the electrodes can be prevented effectively from

corroding, since the second particles are connected electrically with the electrodes via the first particle so as to compose a corrosive cell and the second particles having relatively low potential corrode prior to the electrodes."

In contrast to this requirement, the present claims include restricting the conductive particles having a high melting point of 400°C or more in claims 1 and 4 to Ag powder; and restricting the metal powder having a melting point of 300°C or less of claims 1 and 4 to Sn powder. These embodiments are shown in the Tables of results in the specification to provide especially good results.

It is noted that, not only are special results obtained with the claimed combination, but also the claimed combination is taught away from the important prior art embodiment noted above concerning avoiding corrosion. The standard electrode potential of Ag is higher than that of Sn (see, for example, the online entry at

http://en.wikipedia.org/viki/Standard_electrode_potential

(data page) or the enclosed pages D-151 and D-154 of the 70th edition of the CRC HANDBOOK OF CHEMISTRY AND PHYSICS). Thus, where Ag powder corresponds to the first particles of Takezawa '652 and Sn powder corresponds to the second particles of the same, the electrode potential requirement of Takezawa '652 is not met and modifying Takezawa '652 to meet the present claims is not obvious.

Therefore, the present invention does not satisfy the relationship of the standard electrode potentials; (first particles) > (electrodes) > (second particles) disclosed in Takezawa '652. According to Takezawa '652, if the above relationship is not satisfied, galvanic corrosion will occur in the electrolyte as mentioned at the paragraph [0023] of Takezawa '652. It would be not obvious for a person skilled in the art to use Ag conductive particles and Sn powder as well as an internal electrode of Ni in combination in view of Takezawa '652 or to expect that especially good results for the present invention object, will be obtained.

It is noted that paragraphs [0026], [0028] and [0034] of Takezawa '652, mention Ag, Sn and Ni, respectively, but there is no description to use these metals in combination. In view of the relationship between

(first particles) > (electrodes) > (second particles).

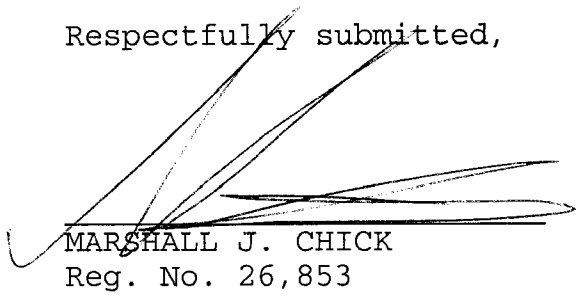
In connection with the standard electrode potential, such a combination of the present invention would as now claimed never be intended.

Furthermore, one would not expect, from Takezawa '652, that a metal-to metal junction is formed between the internal electrode(s) and the external electrode whereby bonding-property is improved by the combination of Ag, Sn and Ni of the present invention.

As to potential corrosion issues raised in Takezawa, the use of the thermosetting resins avoids this as an issue for the present invention. Moisture in air is not an issue in the present invention.

In view of the above, it is submitted that the combination rejections are unsupported or improper. Withdrawal of the rejections and allowance of the application are therefore respectfully requested.

Respectfully submitted,



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